



Fig. 3. The double-sided ladder design. 300 μm thick beryllium pieces provide positioning features at each bulkhead and act as substrates for the HDI at the active bulkhead. One row of SVX chips is mounted opposite the bulkhead mounting surface; a second set is near the end of the ladder. Two rails (not shown) are epoxied to the bottom surfaces of the two silicon detectors and to the two bottom beryllium pieces. Approximately 2600 wirebonds are required on each double-sided ladder.